TITLE: BUMPED DIE AND WIRE
BONDED BOARD-ON-CHIP PACKAGE
Inventor: Larry D.Kinsman
Serial No. 10/792,229
Docket No. 2269-4585.3US
REPLACMENT SHEET

OIPE IAP28
APR 0 3 2006
PATENT & TRADEMARK OFFICE

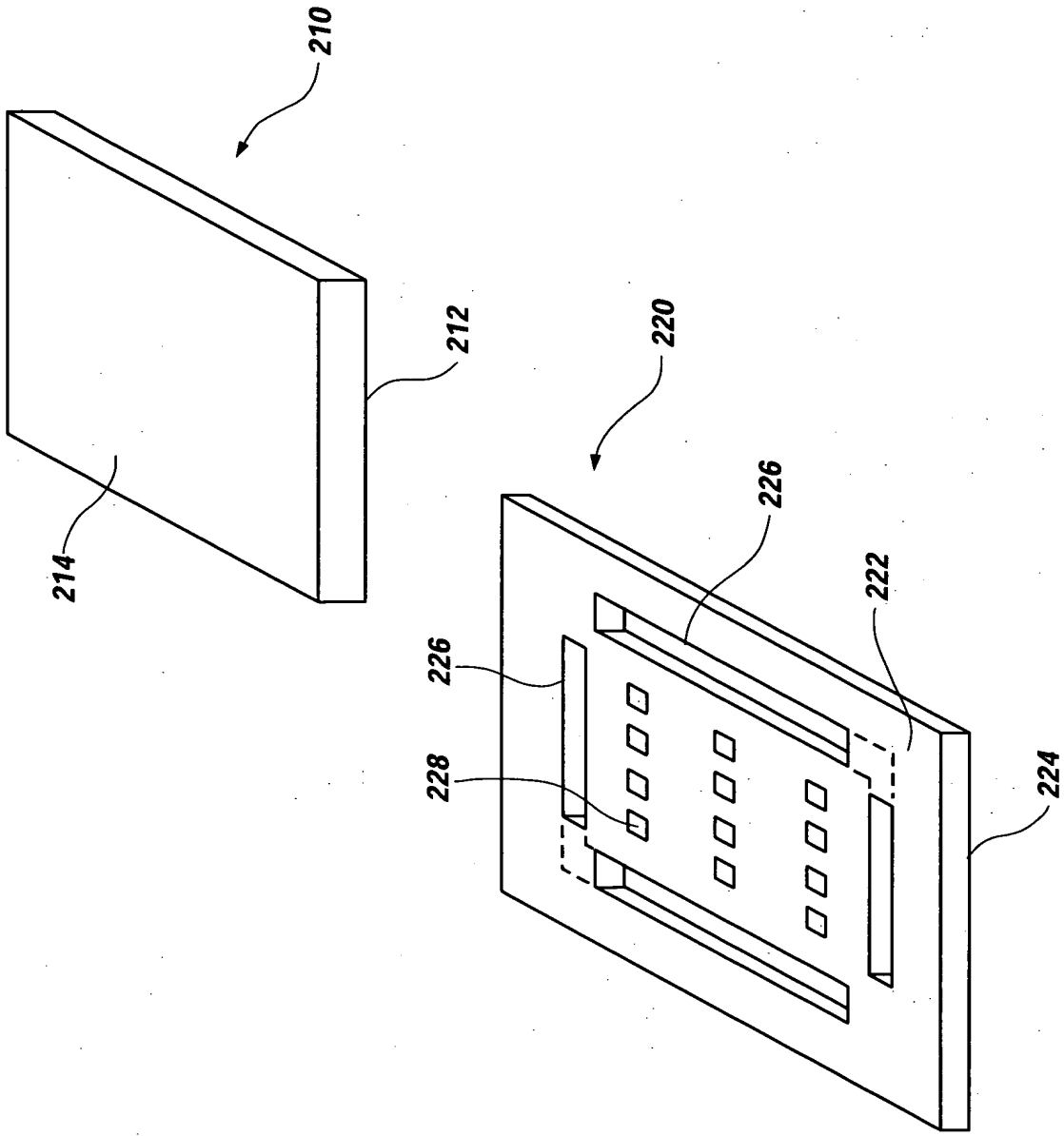

Fig. 6